

REMARKS

The foregoing amendments and following remarks are submitted to address the issues raised in the Office Action mailed June 27, 2008. After entry of the above-amendments, **claims 2 and 7-15 are currently pending in the application, claims 1 and 3-6 having been cancelled.** Claims 5 and 6 stand rejected under 35 U.S.C. § 112, second paragraph, as being indefinite. Claims 1 and 2 stand rejected under 35 U.S.C. § 102(a) as being anticipated by, or in the alternative, under 35 U.S.C. § 103(a) as obvious over Ma et al. (US2003/0141592). Claim 1 stands rejected under 35 U.S.C. § 102(e) as being anticipated by, or in the alternative, under 35 U.S.C. § 103(a) as being obvious over Forray et al. (US 2004/0102566). Claims 3 and 4 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Ma et al. (US 2003/0141592) in view of Sakuyama et al. (US 2003/0080397). Claims 5 and 6 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over MA et al. (US 2003/0141592) in view of Yamamura et al. (US 6,287,745).

Applicant respectfully requests consideration of the application in view of the foregoing amendments and the following remarks.

Claims 5 and 6 -- 35 U.S.C. § 112 second paragraph

The cancellation of claims 5 and 6 is believed to render this rejection moot.

Claim 2 rejected under 35 U.S.C. § 102(a) and (e), and § 103(a)

Ma et al. discloses a number of embodiments directed toward underfill compositions comprising a mixture of two compositions having cure temperatures separated by at least 30°C. (Ma et al., claim 1). The combination of these two composition comprise: thermally curable acrylic compounds with thermally curable epoxy compounds (Ma et al., at [0022] and [0023]), radiation curable cycloaliphatic epoxy compounds and thermally curable aromatic epoxy

compounds (Ma et al., at [0024]), radiation curable acrylic compounds and thermally curable epoxy compounds (Ma et al., at [0025]), and thermally initiated, free radical curable bismaleimide compounds with thermally curable epoxy compounds (Ma et al., at [0026]). While these combinations of compounds may all be useful as underfill compositions in certain applications, their disclosure lacks specificity of the current claim 2.

The present invention, as claimed in amended claim 2, recites a specific underfill composition limited in its constituents and in particular the amount of such constituents so as to provide a flexural modulus of from 1000 to 5000 MPa at 20 °C, and a coefficient of thermal expansion below its glass transition temperature of from 15 to 50 ppm/°C. Without such compositions and properties, the presently claimed underfill would exhibit the negative physical characteristics and problems recited in paragraph [019] of the present specification.

The cited prior art, while directed toward electronics coating materials generally, does not recite the specific narrow ranges or the recited flexural modulus and coefficient of thermal expansion necessary to read on present claim 2.

Applicants respectfully request reconsideration of the rejection of the independent claims under 35 USC 103(a) and allowance of all pending claims.

Conclusion

Applicants respectfully requests early consideration of the present application, entry of all amendments herein requested, and allowance of all pending claims.

The Examiner is respectfully invited to contact Todd W. Galinski at (919) 468-5979 ex6204, to discuss any matter relating to this application.

Respectfully submitted,
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